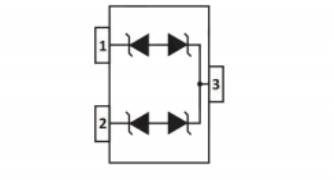
Features

200W peak pulse power(8/20μs)
Protects two bi-directional lines
Ultra low leakage：nA level
Operating voltage：3.3V
Low clamping voltage
Complies with following standards:
– IEC 61000-4-2 (ESD) immunity test
Air discharge: ±25kV
Contact discharge: ±25kV
– IEC61000-4-4 (EFT) 40A (5/50ns)
RoHS Compliant

Applications

Cellular Handsets and Accessories
Notebooks and Handhelds
Portable Instrumentation
Set Top Box
Industrial Controls





Circuit and Pin Schematic

Absolute Maximum Rating

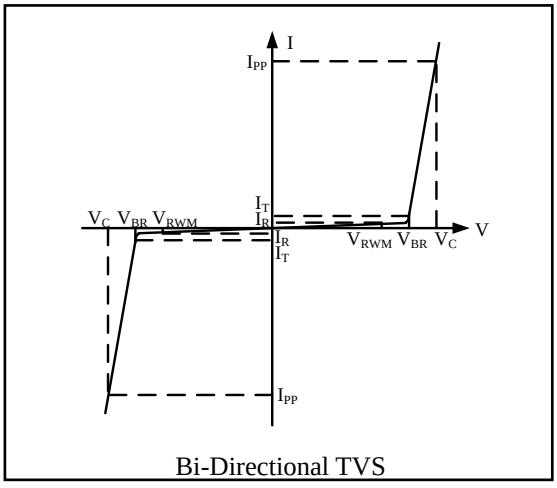
Parameter	Symbol	Value	Unit
Peak Pulse Power(8/20μs)	Ppk	200	W
ESD per IEC 61000−4−2 (Air) ESD per IEC 61000−4−2 (Contact)	VESD	±30 ±30	kV
Operating Temperature Range	TJ	−55 to +125	°C
Storage Temperature Range	Tstg	−55 to +150	°C

Electrical Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V_{RWM}			3.3	V	
Breakdown Voltage	V_{BR}	3.8	4.4	5.0	V	I_T = 1mA
Reverse Leakage Current	I_R			0.1	uA	V_{RWM} =3.3V
Clamping Voltage	V_C			6	V	Ipp=1A(8x 20us pulse)
Clamping Voltage	V_C		8	10	V	Ipp=20A (8x 20us pulse)
Junction Capacitance	C_J		30	50	pF	VR=0, f=1MHz, Pin 1 to Pin 3 or Pin 2 to Pin 3
Junction Capacitance	C_J		17		pF	VR=0, f=1MHz, Pin1 to Pin 2 or Pin 2 to Pin1

Electronics Parameter

Symbol	Parameter
V_{RWM}	Nominal Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Reverse Breakdown Voltage @ I_T
I_T	Test Current for Reverse Breakdown
V_C	Clamping Voltage @ I_{PP}
I_{PP}	Maximum Peak Pulse Current
C_{ESD}	Parasitic Capacitance
V_R	Reverse Voltage
f	Small Signal Frequency



Bi-Directional TVS

RATING AND CHARACTERISTIC CURVES

Fig1. 8/20μs Pulse Waveform

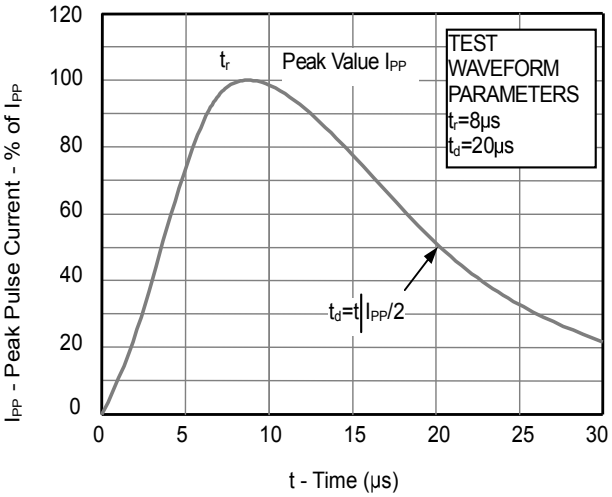


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

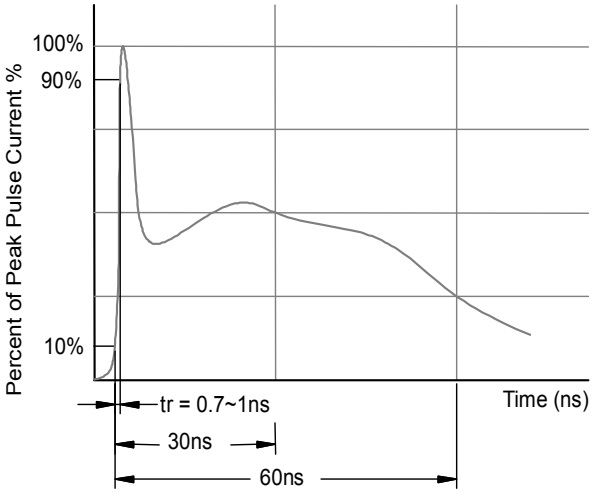
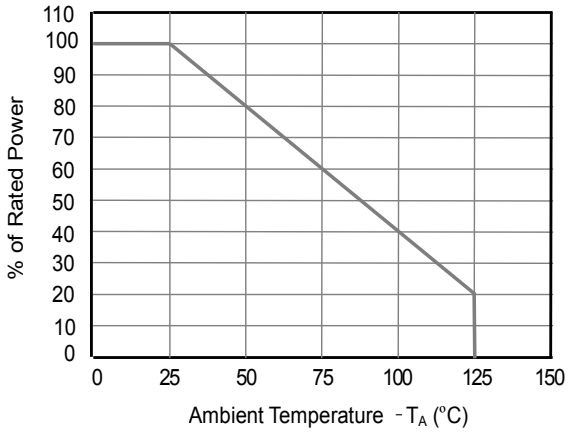


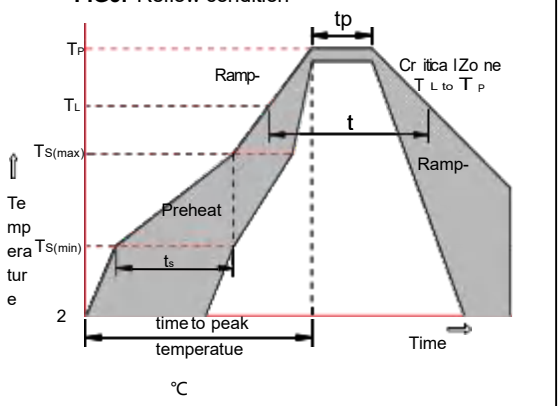
Fig3. Power Derating Curve



Soldering parameters

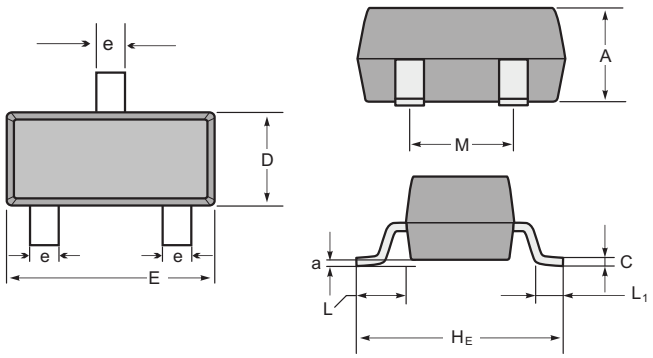
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

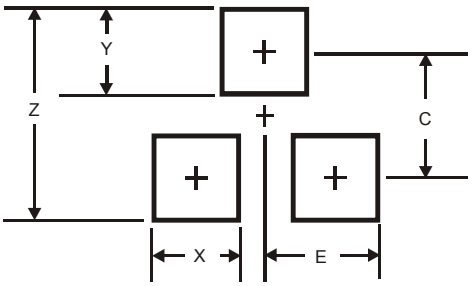
FIG5: Reflow condition



Package Dimensions & Suggested Pad Layout

SOT23





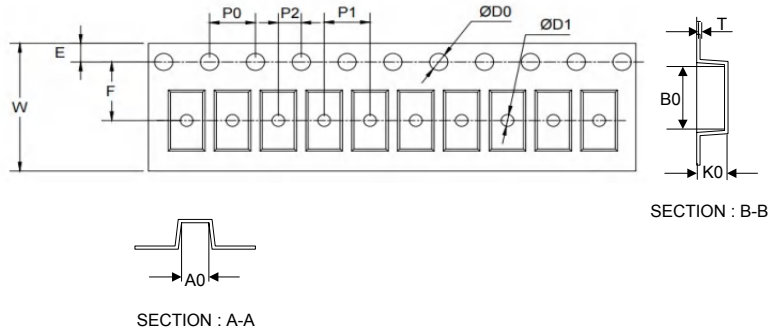
SOT-23 mechanical data

UNIT		A	C	D	E	H_E	e	M	L	L_1	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)	0.0
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7			0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)	0.0
	min	35	3	47	110	87	12	67			6

Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

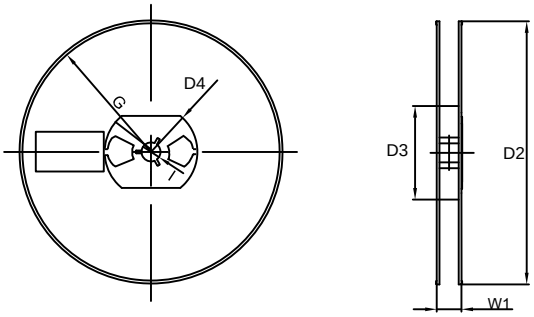
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.10
P1	4.00±0.10
P2	2.00±0.10
D0	1.55±0.10
D1	1.05±0.10
E	1.55±0.10
F	3.60±0.10
W	8.00±0.10
A0	3.80±0.20
B0	3.25±0.20
K0	1.45±0.10
T	0.25±0.05

7” Reel



D2	178.0±3.0
D3	55Min.
D4	R24.0±3.0
G	R82.0±3.0
I	13.0±2.0
W1	11.0±3.0

Quantity: 3000PCS